

Amendments to the Specification:

Please replace the paragraph beginning at page 11, line 14, with the following amended paragraph:

FIGS. ~~18A and 18B~~ 18A-18F are diagrams showing an embodiment of the invention.

Please replace the paragraph beginning at page 11, line 19, with the following amended paragraph:

FIGS. ~~[[23]]~~ 23A-23C are diagrams showing a crystallization energy and TFT characteristics.

At page 18, after "[Table 1]" and between lines 3 and 4, please insert the following:

Table.1

Image No.	energy density [mJ/cm2]	Image No.	energy density [mJ/cm2]
1	379(-12.40%)	7	443.6(+2.519%)
2	390.3(-9.80%)	8	455.7(+5.32%)
3	404.5(-6.52%)	9	466.3(+7.77%)
4	411.2(-4.97%)	10	475.4(+9.87%)
5	423.9(-2.03%)	11	487.2(+12.60%)
6	<u>432.7(±0)</u>		

underline; image regarded as optimal

At page 18, after "[Table 2]" and between lines 8 and 9, please insert the following:

Table. 2

Ranking	Magnification		
	× 100	× 200	× 500
1	<u>No.6</u>	<u>No.6</u>	No.5
2	No.5	No.5	<u>No.6</u>
3	No.7	No.7	No.7

underline; image regarded as optimal

Please replace the paragraph at page 19, line 7, with the following amended paragraph:

[Table 3] and [Table 4]

At page 19, after "[Table 3] and [Table 4]" and between lines 7 and 8, please insert the following:

Table. 3

Rank -ing	Magnification		
	× 100	× 200	× 500
1	No.5	No.6	No.6
	lave=147092.37, $\chi^2=1576137067.69$	lave=150773.21 $\chi^2=1183441246.96$	lave=150750.69 $\chi^2=1136033157.57$
2	No.6	No.7	No.5
	lave=152666.57 $\chi^2=2380243804.95$	lave=151851.67, $\chi^2=2251576505.41$	lave=144950.20 $\chi^2=1198144579.60$
3	No.7	No.5	No.7
	lave=153714.22 $\chi^2=6024570507.37$	lave=149289.91 $\chi^2=2791476021.76$	lave=151951.89 $\chi^2=2561081865.95$

Average value and variation degree are shown in a parenthesis.

Table. 4

Image No.	average value of modified bright degree in whole image	number of lines (luminance)
No.7	215	884
No.6	215	981
No.5	215	306

(× 500)

Please replace the paragraph beginning at page 31, line 9 with the following amended paragraph:

Heat treatment may be carried out before forming the first passivation layer 119; however, it is preferable to carry out the heat treatment after forming the first passivation layer 119 in order to protect wirings and the like in the case where the materials constituting first conductive layers ~~307a to 310a~~ 107a to 110a and second conductive layers ~~307b to 310b~~ 107b to 110b are sensitive to heat. Further, in the case of heating before forming the first passivation layer, hydrogenation by using hydrogen contained in the passivation layer cannot be performed as the first passivation layer is not formed yet.

Please replace the paragraph beginning at page 40, line 12, with the following amended paragraph:

The power supply voltage and various kind of signals are supplied to the printed circuit substrate 806 via an interface (I/F) 808 in which a plurality of input terminals are arranged.